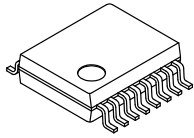


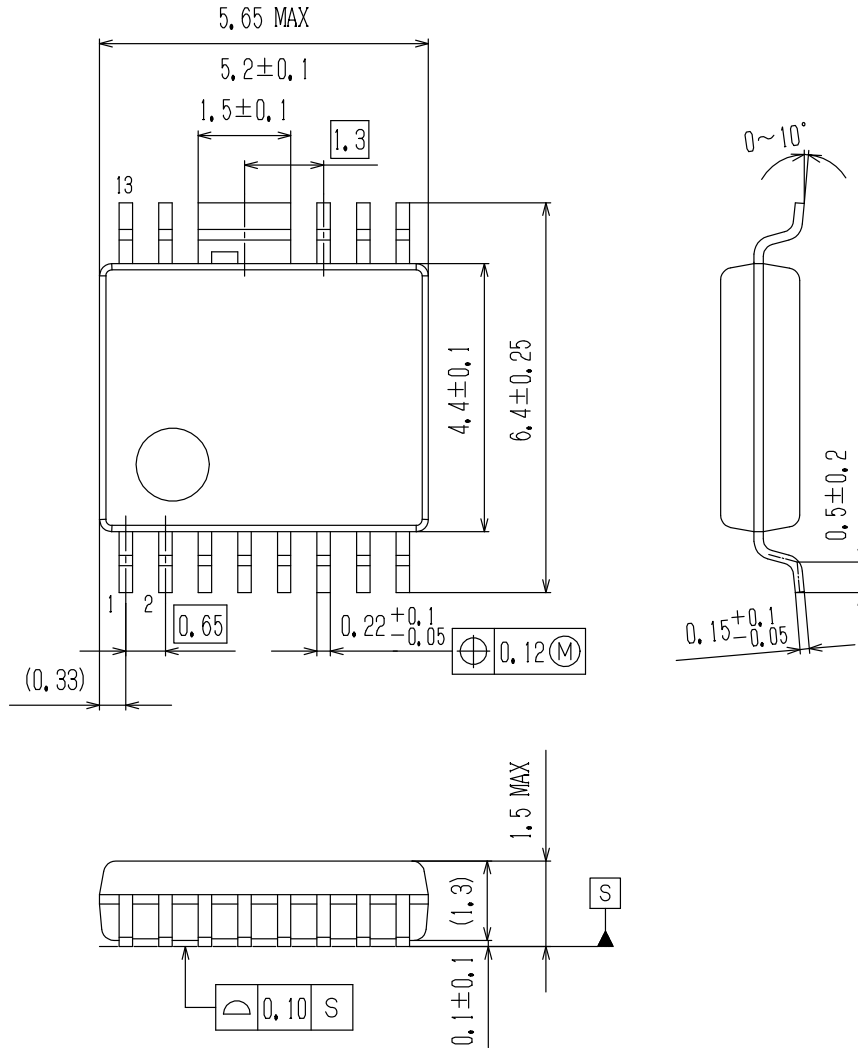
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



HSSOP13 (225 mil) 5.2x4.4, 0.65P
CASE 944AD
ISSUE O

DATE 31 MAY 2012



DOCUMENT NUMBER:	98AON80834E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	HSSOP13 (225 MIL) 5.2X4.4, 0.65P	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.